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BGA/CSP Development Update Service

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The third quarterly BGA/CSP update for 2003 features special coverage of assembly issues for silicon devices with low-k dielectrics, including bonding over active I/Os and flip chip. Highlighted are activities at major companies. The report also includes a section on packaging trends for mobile phones, including package types, pitch trends, and motherboard technology. Featured are new 0.4mm pitch CSPs. A special section on packaging trends for DRAM memory products described the shift from TSOPs to FBGAs. The section also contains developments in wafer level packages, featuring the new wafer level packages from TwinMOS and Infineon. The report also includes a discussion on HAST for laminate substrates and when the test is appropriate.

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